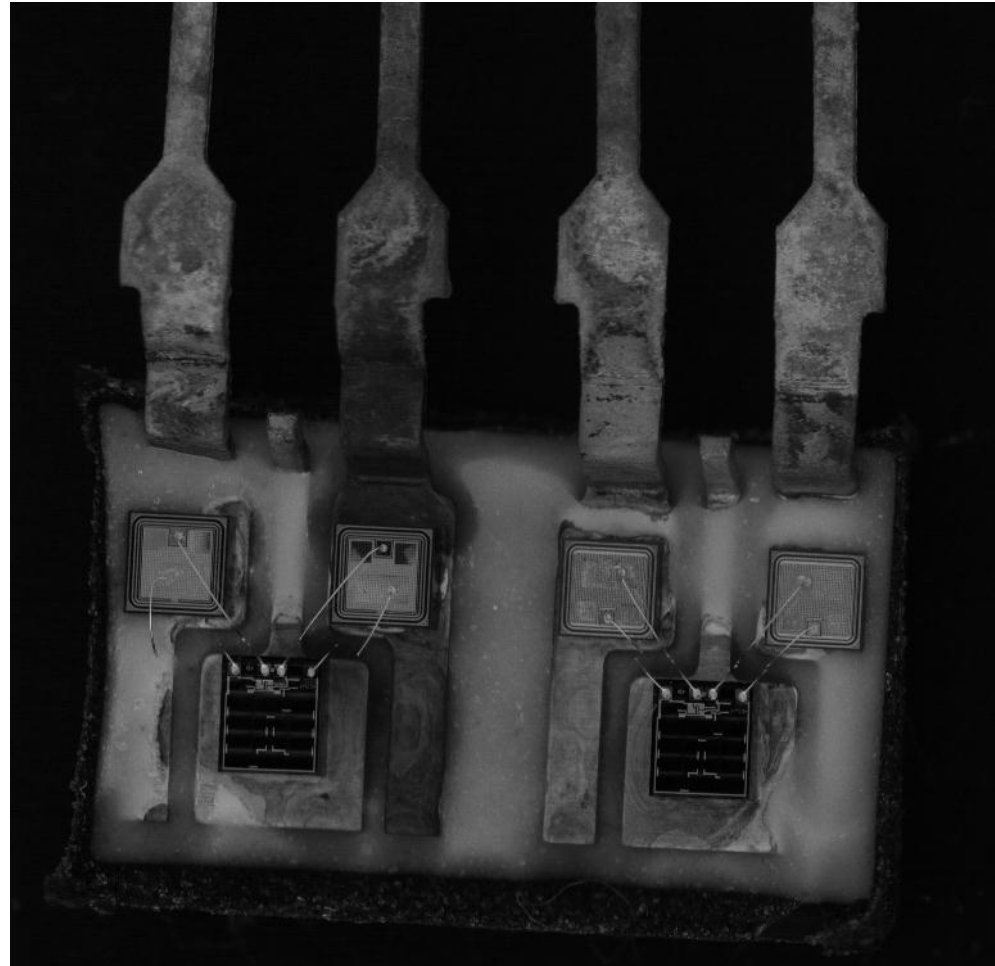
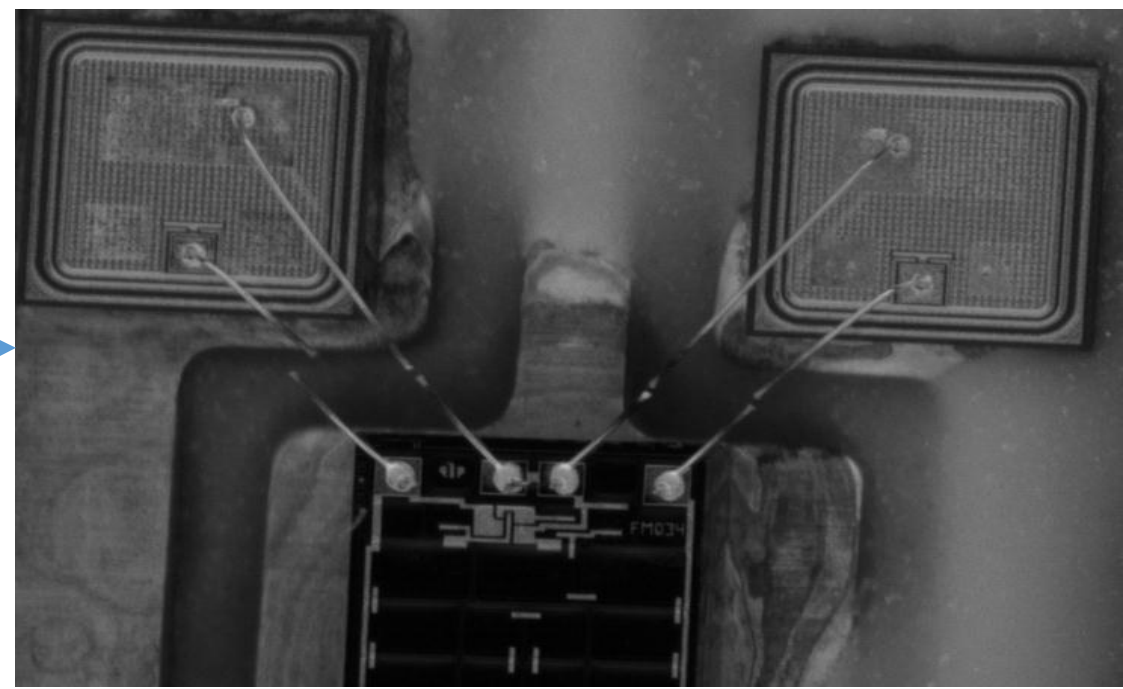
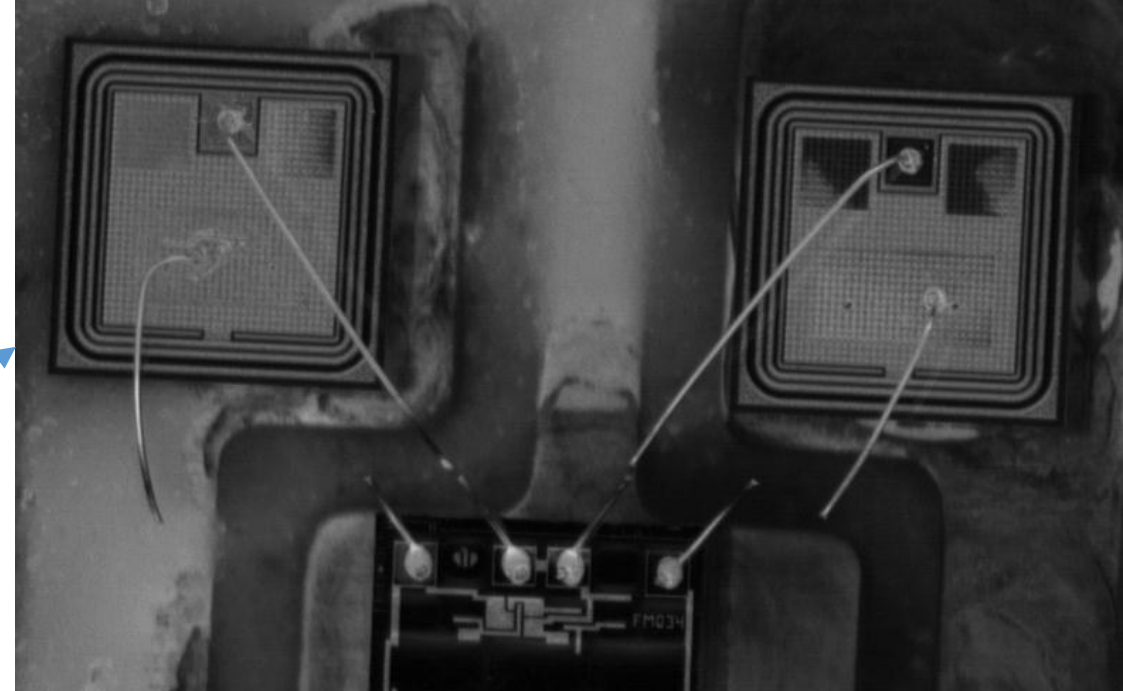
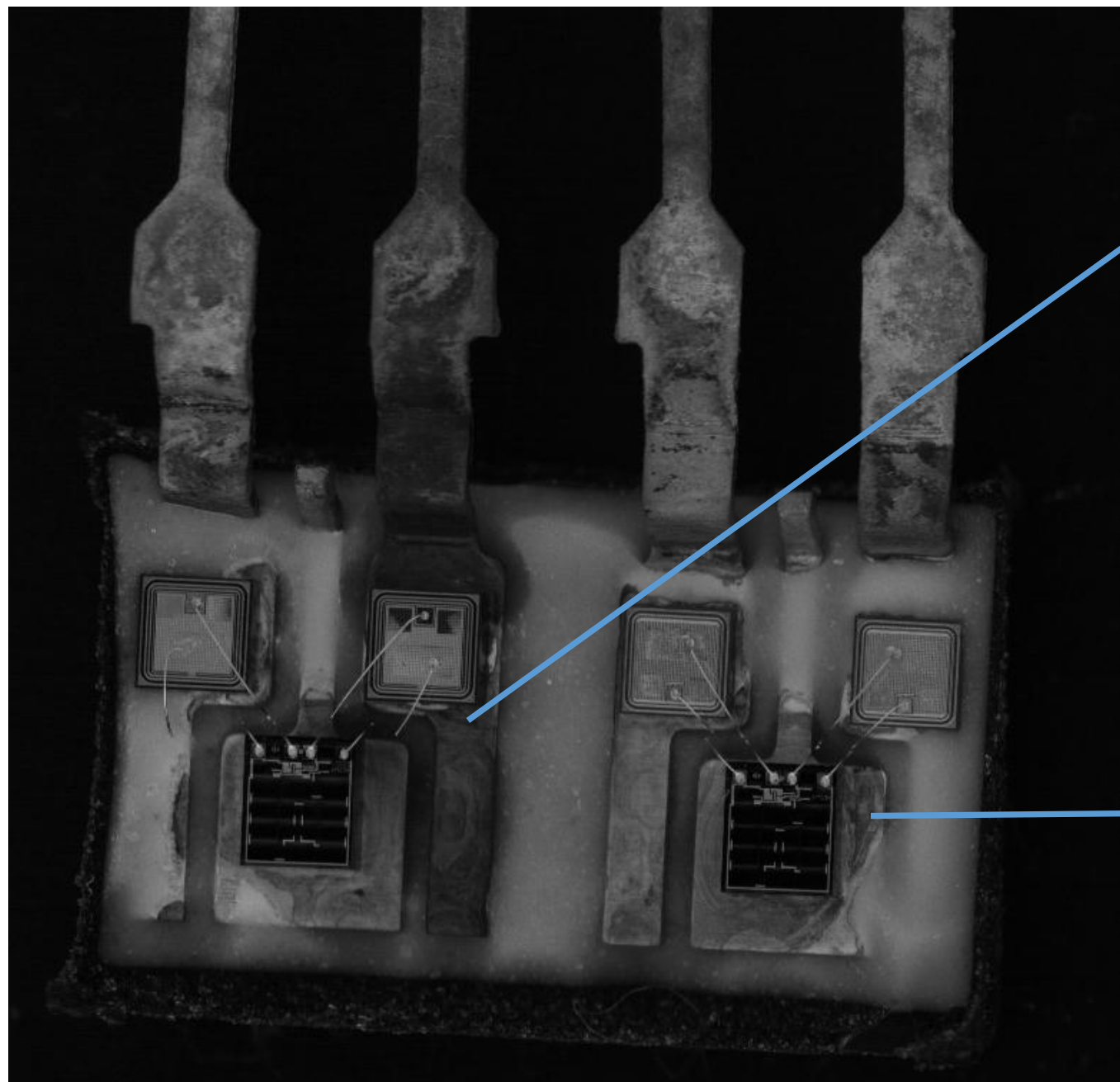


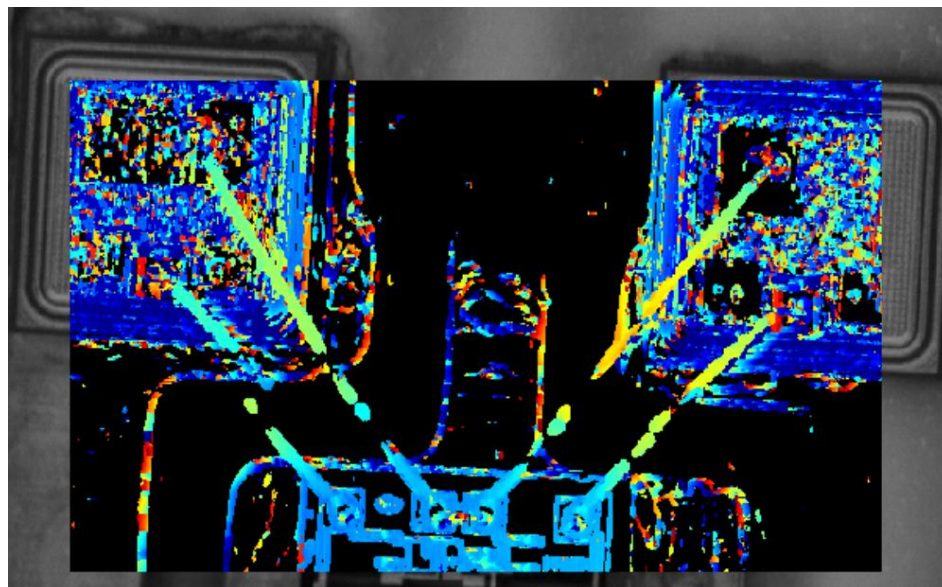
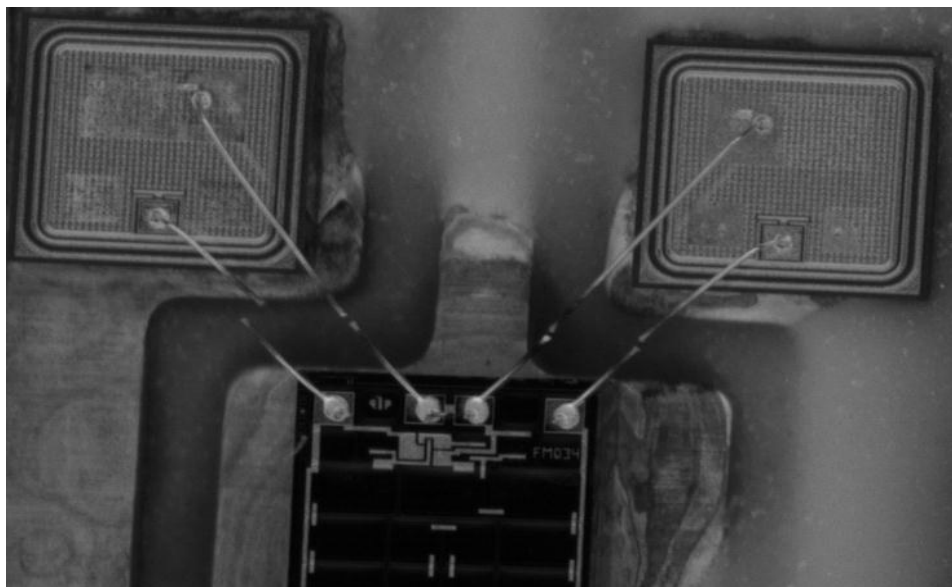
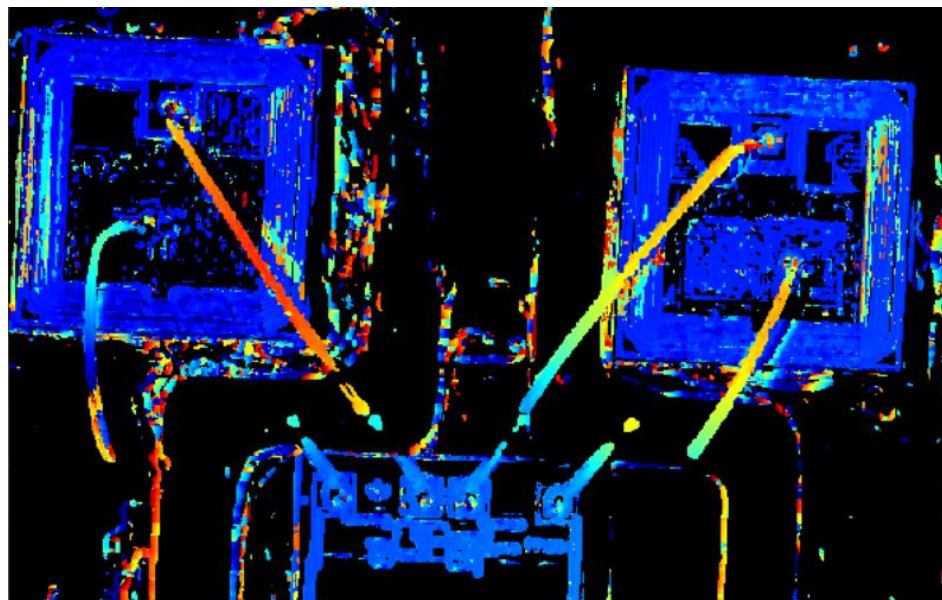
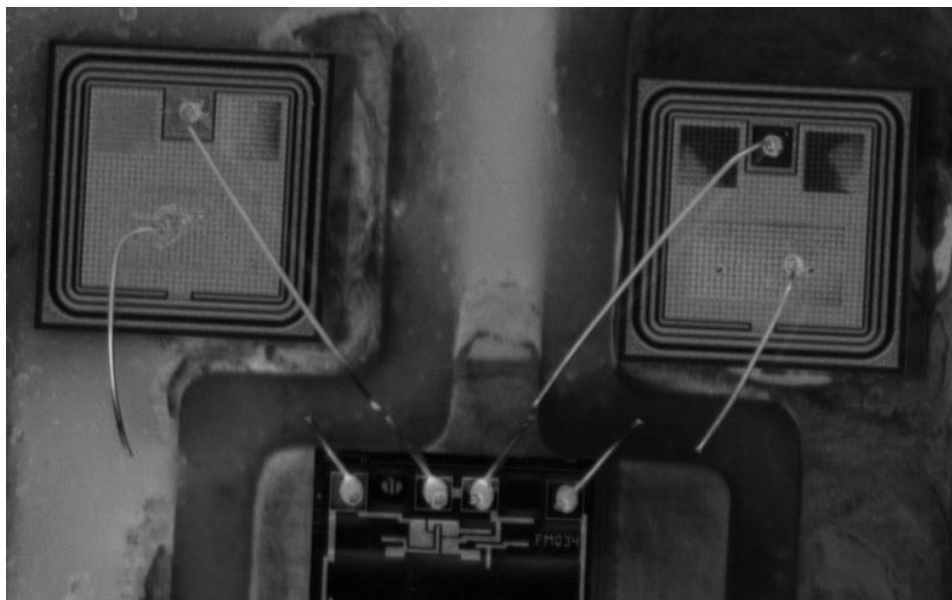
Wirebonding 3D Inspection



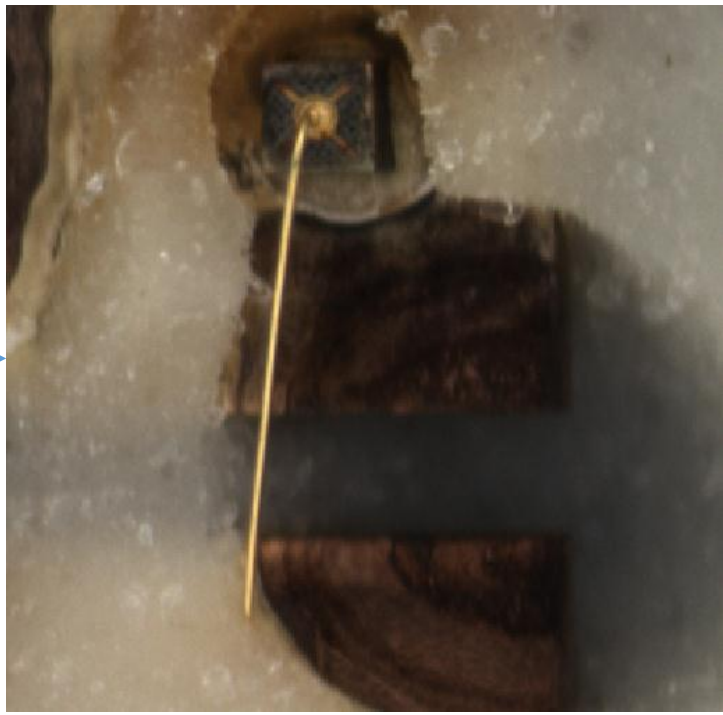
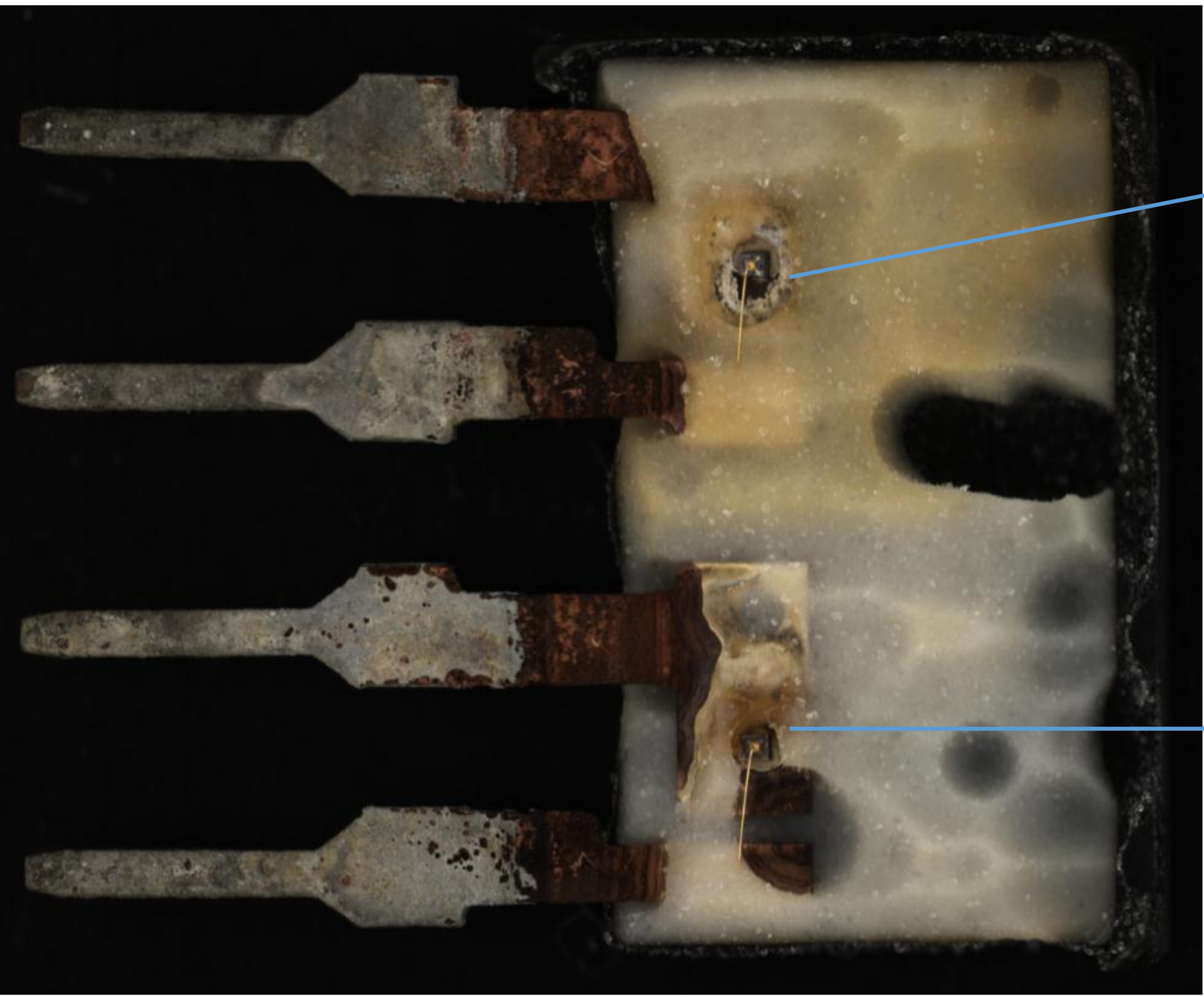
2D Image: PD端



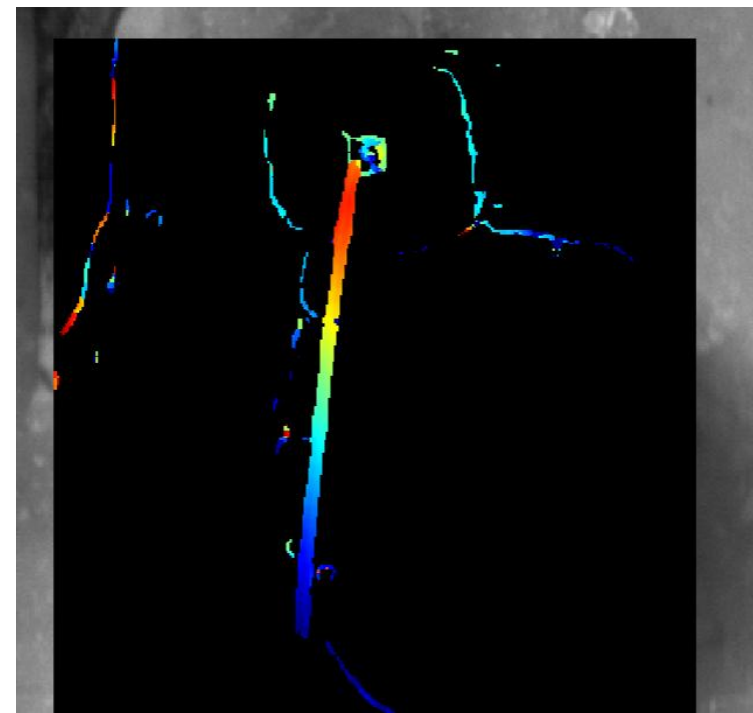
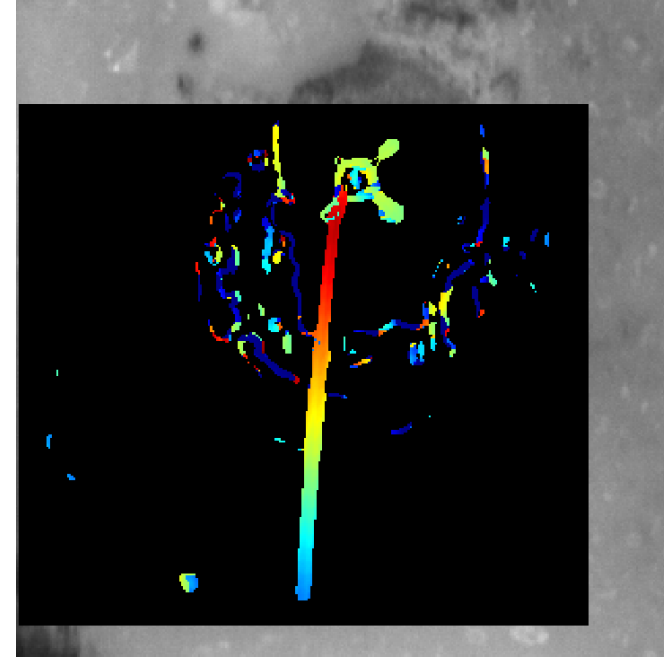
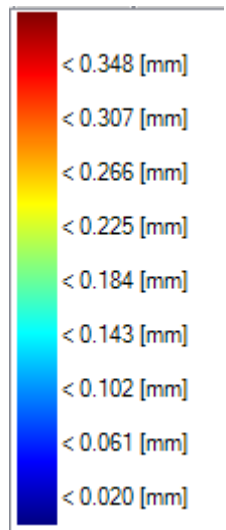
3D Image: PD端



2D Image: IR端



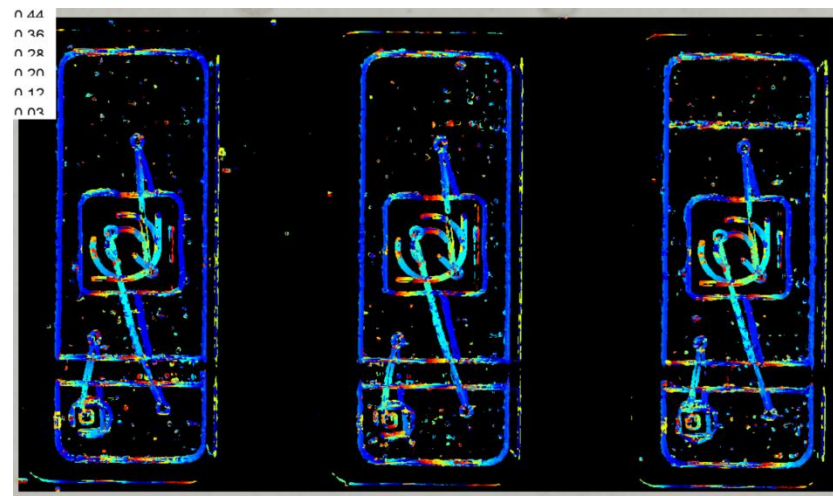
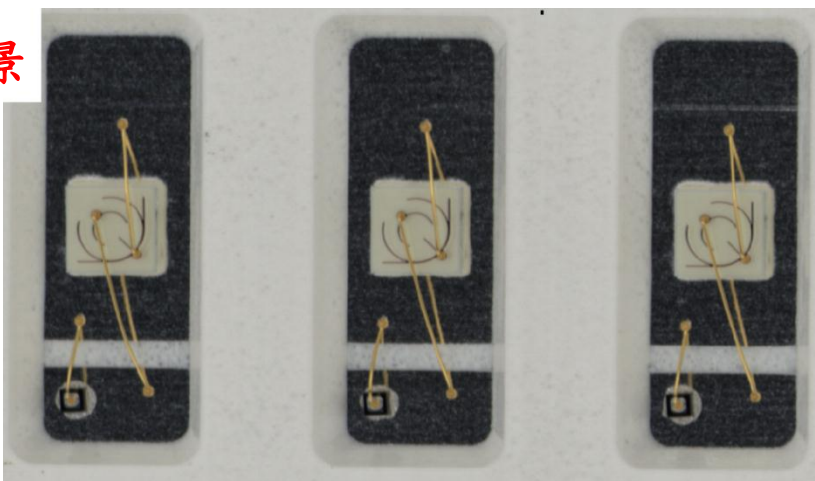
3D Image: IR端



3D Inspection Process Point

以影像處理方式將Wire與背景分離，取出的Wire進行3D計算將可得到更佳之計算結果

未去除背景



去除背景

